April 2007



SEMICONDUCTOR

## FFPF08H60S Hyperfast 2 Rectifier

### Features

- + High Speed Switching (  $t_{rr} \mbox{=} 45 \mbox{ns}(\mbox{Max.}) @ I_F \mbox{=} 8 \mbox{A}$  )
- High Reverse Voltage and High Reliability
- Avalanche Energy Rated
- Low Forward Voltage(V<sub>F</sub>=2.1V(Max.) @ I<sub>F</sub>=8A)

### **Applications**

- General Purpose
- Switching Mode Power Supply
- Free-wheeling diode for motor application
- Power switching circuits

**Pin Assignments** 

## 8A, 600V Hyperfast 2 Rectifier

The FFPF08H60S is hyperfast2 rectifier (trr=45ns(Max.) @ IF=8A). it has half the recovery time of ultrafast rectifier and is silicon nitride passivated ion-implanted epitaxial planar construction.

This device is intended for use as freewheeling/clamping rectifiers in a variety of switching power supplies and other power switching applications. Its low stored charge and hyperfast soft recovery minimize ringing and electrical noise in many power switching circuits reducing power loss in the switching transistors.

Symbol	Parameter	Value	Units
V <sub>RRM</sub>	Peak Repetitive Reverse Voltage	600	V
V <sub>RWM</sub>	Working Peak Reverse Voltage	600	V
V <sub>R</sub>	DC Blocking Voltage	600	V
I <sub>F(AV)</sub>	Average Rectified Forward Current @ T <sub>C</sub> = 105 °C	8	A
I <sub>FSM</sub>	Non-repetitive Peak Surge Current   60Hz Single Half-Sine Wave		Â
T <sub>J,</sub> T <sub>STG</sub>	Operating Junction and Storage Temperature	- 65 to +150	°C

### Thermal Characteristics T<sub>C</sub> = 25°C unless otherwise noted

Symbol	Parameter	Мах	Units
$R_{ ext{ heta}JC}$	Maximum Thermal Resistance, Junction to Case	3.4	°C/W

### Package Marking and Ordering Information

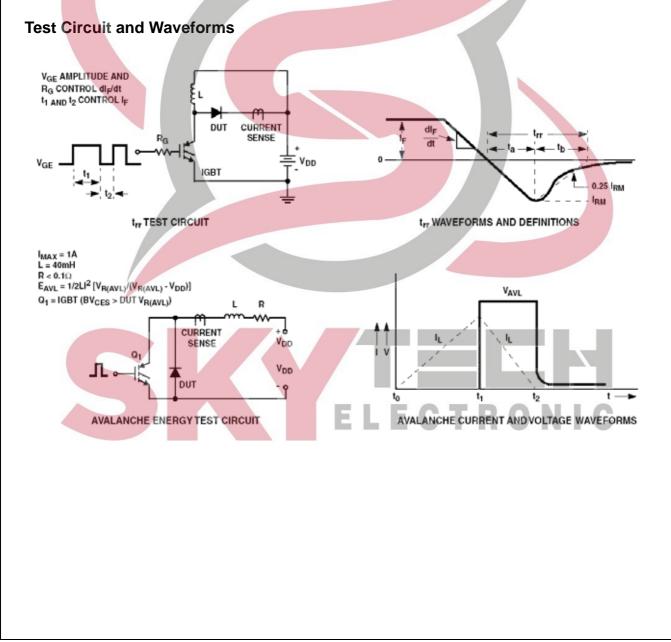
Device Marking	Device	Package	Reel Size	Tape Width	Quantity
F08H60S	FFPF08H60STU	TO-220F	-	-	50

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Parameter	Conditions			Тур.	Max	Units
V <sub>FM</sub> <sup>1</sup>	I <sub>F</sub> = 8A I <sub>F</sub> = 8A	T <sub>C</sub> = 25 °C T <sub>C</sub> = 125 °C	-	-	2.1 1.7	V V
I <sub>RM</sub> <sup>1</sup>	$V_{R} = 600V$ $V_{R} = 600V$	T <sub>C</sub> = 25 °C T <sub>C</sub> = 125 °C	-	-	100 200	μΑ μΑ
t <sub>rr</sub>	$I_F = 1A, di/dt = 100A/\mu s, V_{CC} = 30V$ $I_F = 8A, di/dt = 100A/\mu s, V_{CC} = 390V$	T <sub>C</sub> = 25 °C T <sub>C</sub> = 25 °C	-	-	35 45	ns ns
t <sub>a</sub> t <sub>b</sub> Q <sub>rr</sub>	I <sub>F</sub> =8A, di/dt = 100A/µs, V <sub>CC</sub> = 390V	T <sub>C</sub> = 25 °C T <sub>C</sub> = 25 °C T <sub>C</sub> = 25 °C T <sub>C</sub> = 25 °C	- - -	15 16 18.6	-	ns ns nC
W <sub>AVL</sub>	Avalanche Energy (L = 40mH)		20	-	-	mJ

#### Notes:

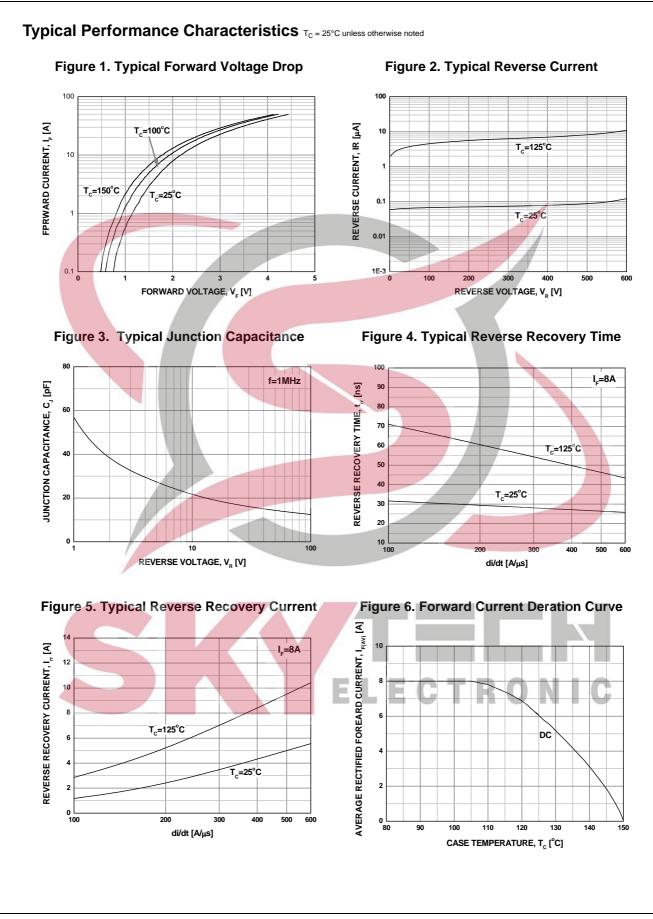
1. Pulse : Test Pulse width =  $300\mu$ s, Duty Cycle = 2%



#### FFPF08H60S Rev. A

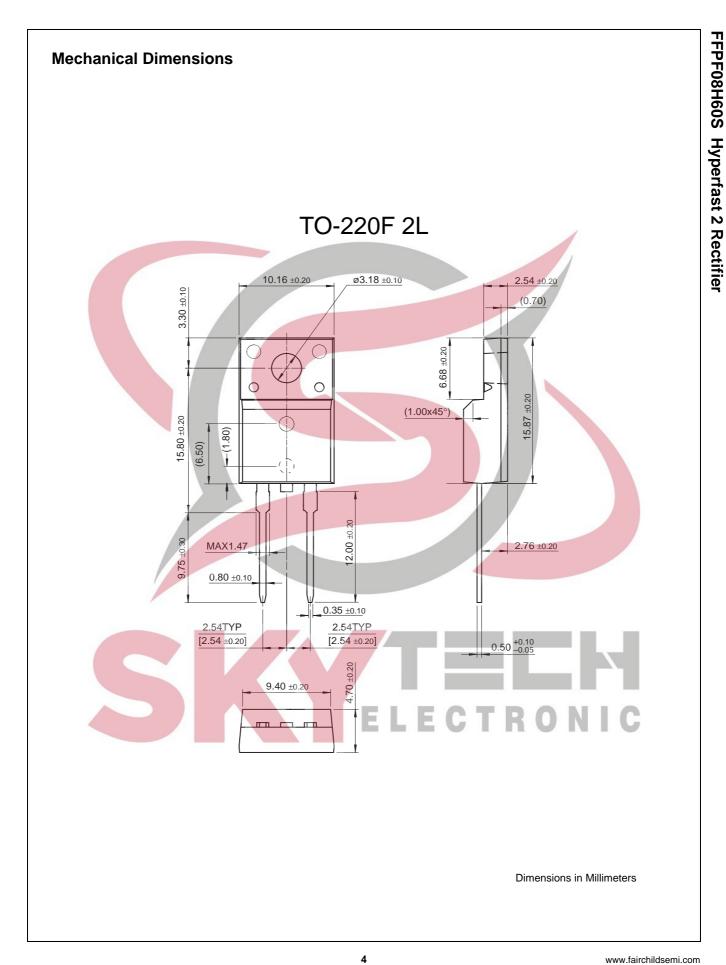
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FFPF08H60S Hyperfast 2 Rectifier 600



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FFPF08H60S Rev. A



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Bottomless™	<i>i-Lo</i> ™	PowerTrench <sup>®</sup>	тм
Build it Now™	ImpliedDisconnect <sup>™</sup>	Programmable Active Droop™	U
CoolFET™	IntelliMAX™	QFET®	TinyBoost™
CROSSVOLT	ISOPLANAR™	QS™	TinyBuck™
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FPS™	POP™	SuperSOT™-6	
FRFET®	Power220 <sup>®</sup>	SuperSOT™-8	

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Datasheet Identification	Product Status	Definition
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